

<b>INFORMATION DISCLOSURE CITATION</b>  PTO-1449				ATTY. DOCKET NO. A-68779/REB/VEJ		SERIAL NO. 09/174,337	
				APPLICANT Jorné et al.			
				FILING DATE October 19, 1998		GROUP 1741	
<b>U.S. PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
DEV	5,230,743	07/27/93	Thompson et al.	134	32	07/30/92	
DEV	5,429,733	07/04/95	Ishida	204	224R	05/04/93	
DEV	5,445,172	08/29/95	Thompson et al.	134	153	03/08/93	
<b>FOREIGN PATENT DOCUMENTS</b>							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes <input type="checkbox"/> No <input type="checkbox"/>	
<b>OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)</b>							
DEV	J. Jorné, Current Distribution of Copper Electroplating on Wafers, Report, Cupricon, Inc., Rochester, NY (July 24, 1997)						
DEV	H.S. Rathole and D. Nguyen, Copper Metallization for Sub-Micron Technology in Advance Metallization Processes, VLSI Multilevel Interconnection, Santa Clara, CA, June 9, 1997						
DEV	P. Singer, Making the Move to Dual Damascene Processing, Semiconductor International, pp. 79-82, August 1997						
DEV	P. Singer, Copper Goes Mainstream: Low k to Follow, Semiconductor International, pp. 67-70, November 1997						
DEV	V.M. Dubin, C.H. Ting and R. Cheung, Electrochemical Deposition of Copper for ULSI Metallization, paper 3.A, VLSI Multilevel Interconnection Conference, June 10-12, 1997						
DEV	M. Witty, S.P. Murarka and D.B. Fraser, SRC Workshop on Copper Interconnect Technology, Semiconductor Research Corporation, Research Triangle Park, NC, August 17-18, 1993						
DEV	VLSI Multilevel Interconnection Conference, VMCI, Santa Clara, CA, June 10-12, 1997						
EXAMINER <i>Donald R. Valentine</i>				DATE CONSIDERED <i>4-25-00</i>			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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